

3.2x1.6mm SMD CHIP LED LAMP

KP-3216MGC

MEGA GREEN

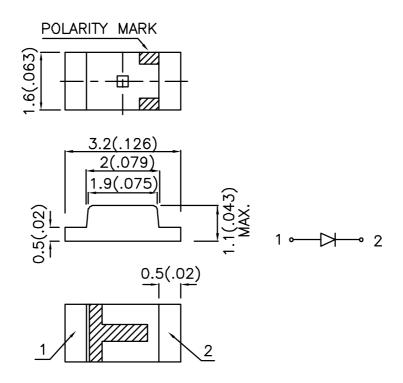
Features

- •3.2mmx1.6mm SMT LED, 1.1mm THICKNESS.
- •LOW POWER CONSUMPTION.
- •WIDE VIEWING ANGLE.
- •IDEAL FOR BACKLIGHT AND INDICATOR.
- •VARIOUS COLORS AND LENS TYPES AVAILABLE.
- •PACKAGE: 2000PCS/REEL.
- •RoHS COMPLIANT.

Description

The Mega Green source color devices are made with DH InGaAIP on GaAs substrate Light Emitting Diode.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- Tolerance is ±0.2(0.0079") unless otherwise noted.
 Specifications are subject to change without notice.

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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) @ 20mA		Viewing Angle
			Min.	Тур.	201/2
KP-3216MGC	MEGA GREEN (InGaAIP)	WATER CLEAR	18	70	120°

Note:

Electrical / Optical Characteristics at Ta=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Mega Green	574		nm	IF=20mA
λD	Dominant Wavelength	Mega Green	568		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Mega Green	26		nm	IF=20mA
С	Capacitance	Mega Green	20		pF	VF=0V;f=1MHz
VF	Forward Voltage	Mega Green	2.1	2.5	V	IF=20mA
IR	Reverse Current	Mega Green		10	uA	VR = 5V

Absolute Maximum Ratings at Ta=25°C

Parameter	Mega Green	Units	
Power dissipation	105	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		

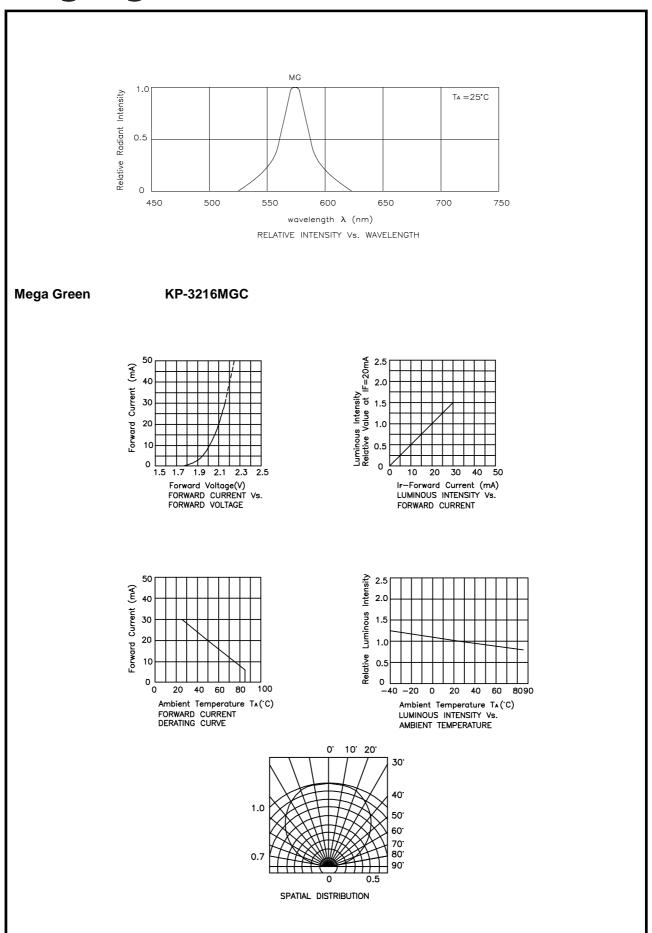
Note

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 $^{1.\,\}theta1/2$ is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

^{1. 1/10} Duty Cycle, 0.1ms Pulse Width.

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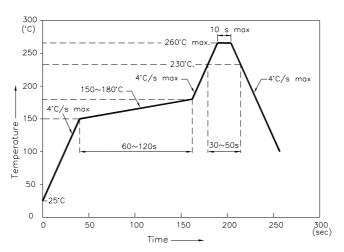


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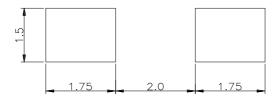
Reflow Soldering Profile For Lead-free SMT Process.



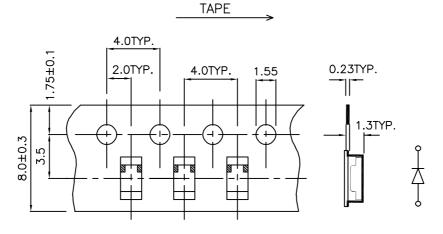
NOTES

- 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.
- 2.Don't cause stress to the epoxy resin while it $\,$ is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm)



Tape Specifications (Units: mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

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